

MJD31, MJD31C (NPN), MJD32, MJD32C (PNP)



ON Semiconductor®

<http://onsemi.com>

Complementary Power Transistors

DPAK For Surface Mount Applications

Designed for general purpose amplifier and low speed switching applications.

Features

- Lead Formed for Surface Mount Applications in Plastic Sleeves
- Straight Lead Version in Plastic Sleeves ("1" Suffix)
- Lead Formed Version in 16 mm Tape and Reel ("T4" Suffix)
- Electrically Similar to Popular TIP31 and TIP32 Series
- Epoxy Meets UL 94, V-0 @ 0.125 in
- ESD Ratings: Human Body Model, 3B > 8000 V
Machine Model, C > 400 V
- These are Pb-Free Packages

MAXIMUM RATINGS

Rating	Symbol	Max	Unit
Collector-Emitter Voltage MJD31, MJD32 MJD31C, MJD32C	V_{CEO}	40 100	Vdc
Collector-Base Voltage MJD31, MJD32 MJD31C, MJD32C	V_{CB}	40 100	Vdc
Emitter-Base Voltage	V_{EB}	5	Vdc
Collector Current – Continuous – Peak	I_C	3 5	Adc
Base Current	I_B	1	Adc
Total Power Dissipation @ $T_C = 25^\circ\text{C}$ Derate above 25°C	P_D	15 0.12	W W/ $^\circ\text{C}$
Total Power Dissipation @ $T_A = 25^\circ\text{C}$ Derate above 25°C	P_D	1.56 0.012	W W/ $^\circ\text{C}$
Operating and Storage Junction Temperature Range	T_J, T_{stg}	-65 to +150	$^\circ\text{C}$

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

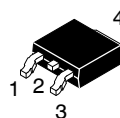
THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	8.3	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction-to-Ambient*	$R_{\theta JA}$	80	$^\circ\text{C}/\text{W}$
Lead Temperature for Soldering Purposes	T_L	260	$^\circ\text{C}$

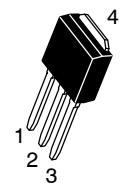
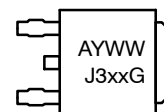
*These ratings are applicable when surface mounted on the minimum pad sizes recommended.

**SILICON
POWER TRANSISTORS
3 AMPERES
40 AND 100 VOLTS
15 WATTS**

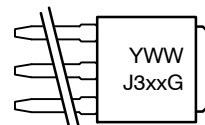
MARKING DIAGRAMS



**DPAK
CASE 369C
STYLE 1**



**DPAK-3
CASE 369D
STYLE 1**



A = Site Code
Y = Year
WW = Work Week
xx = 1, 1C, 2, or 2C
G = Pb-Free Package

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 8 of this data sheet.

MJD31, MJD31C (NPN), MJD32, MJD32C (PNP)

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
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OFF CHARACTERISTICS

Collector-Emitter Sustaining Voltage (Note 1) (I _C = 30 mA, I _B = 0)	MJD31, MJD32 MJD31C, MJD32C	V _{CEO(sus)}	40 100	- -	Vdc
Collector Cutoff Current (V _{CE} = 40 Vdc, I _B = 0) (V _{CE} = 60 Vdc, I _B = 0)	MJD31, MJD32 MJD31C, MJD32C	I _{CEO}	-	50	μA _{dc}
Collector Cutoff Current (V _{CE} = Rated V _{CEO} , V _{EB} = 0)		I _{CES}	-	20	μA _{dc}
Emitter Cutoff Current (V _{BE} = 5 Vdc, I _C = 0)		I _{EBO}	-	1	mA _{dc}

ON CHARACTERISTICS (Note 1)

DC Current Gain (I _C = 1 A _{dc} , V _{CE} = 4 Vdc) (I _C = 3 A _{dc} , V _{CE} = 4 Vdc)		h _{FE}	25 10	- 50	-
Collector-Emitter Saturation Voltage (I _C = 3 A _{dc} , I _B = 375 mA _{dc})		V _{CE(sat)}	-	1.2	Vdc
Base-Emitter On Voltage (I _C = 3 A _{dc} , V _{CE} = 4 Vdc)		V _{BE(on)}	-	1.8	Vdc

DYNAMIC CHARACTERISTICS

Current Gain – Bandwidth Product (Note 2) (I _C = 500 mA _{dc} , V _{CE} = 10 Vdc, f _{test} = 1 MHz)		f _T	3	-	MHz
Small-Signal Current Gain (I _C = 0.5 A _{dc} , V _{CE} = 10 Vdc, f = 1 kHz)		h _{fe}	20	-	-

1. Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2%.
2. f_T = |h_{fe}| • f_{test}.

MJD31, MJD31C (NPN), MJD32, MJD32C (PNP)

TYPICAL CHARACTERISTICS

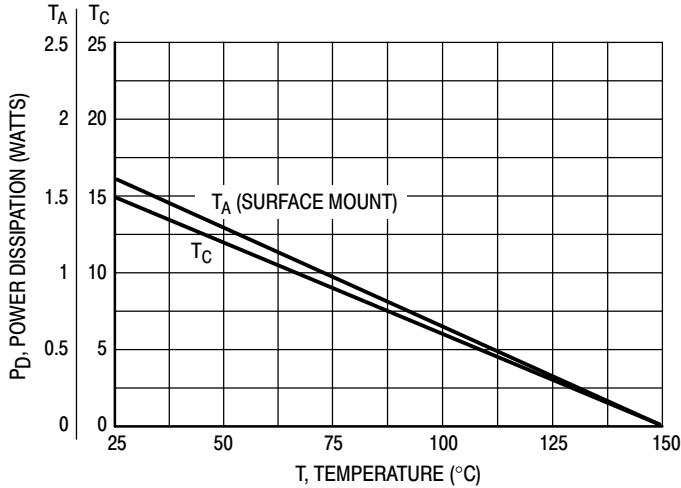
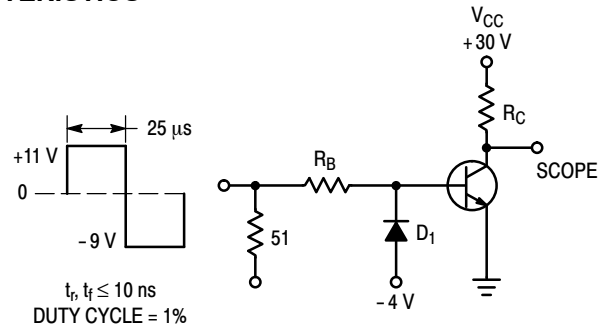


Figure 1. Power Derating



R_B and R_C VARIED TO OBTAIN DESIRED CURRENT LEVELS
 D_1 MUST BE FAST RECOVERY TYPE, e.g.:
 1N5825 USED ABOVE $I_B \approx 100$ mA
 MSD6100 USED BELOW $I_B \approx 100$ mA
 REVERSE ALL POLARITIES FOR PNP.

Figure 2. Switching Time Test Circuit

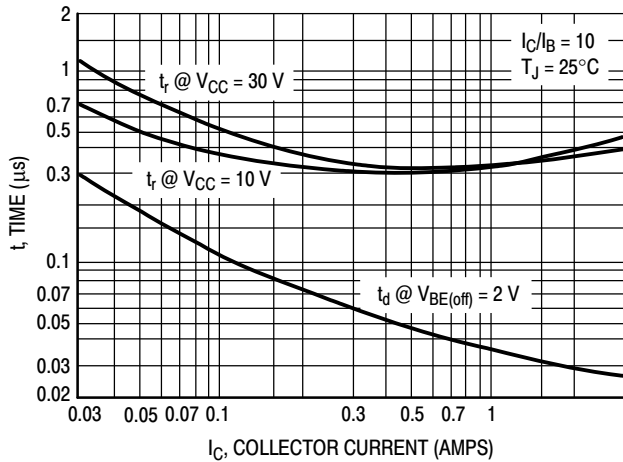


Figure 3. Turn-On Time

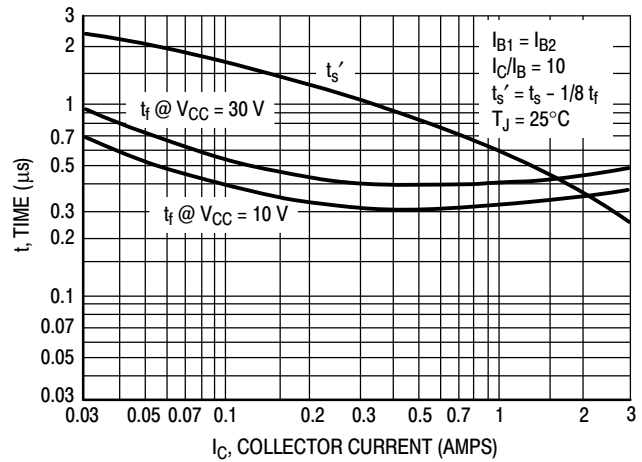


Figure 4. Turn-Off Time

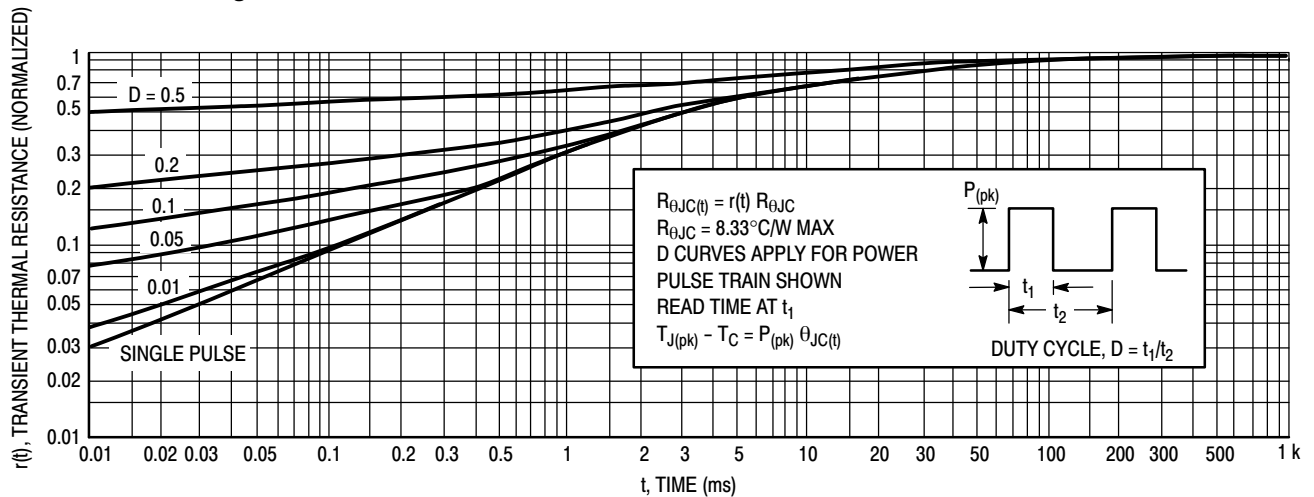


Figure 5. Thermal Response

MJD31, MJD31C (NPN), MJD32, MJD32C (PNP)

TYPICAL CHARACTERISTICS – MJD31, MJD31C (NPN)

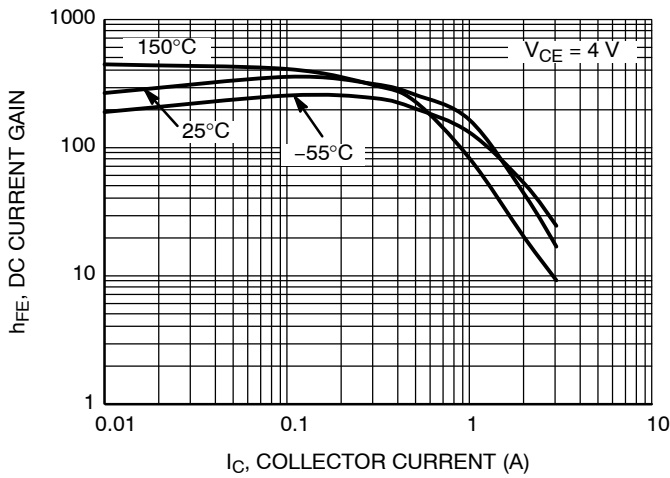


Figure 6. DC Current Gain at $V_{CE} = 4\text{ V}$

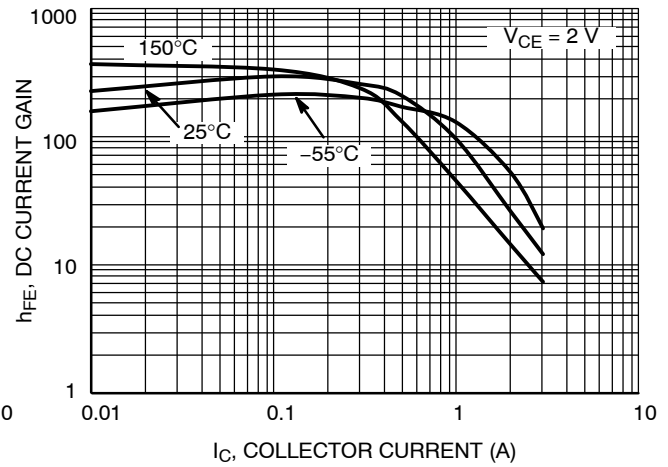


Figure 7. DC Current Gain at $V_{CE} = 2\text{ V}$

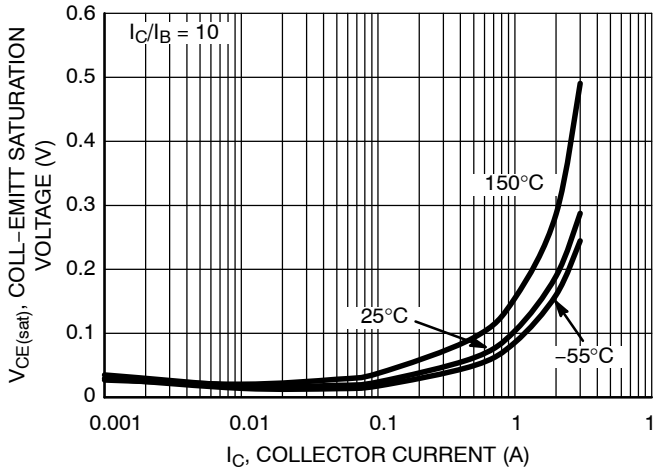


Figure 8. Collector-Emitt Saturation Voltage

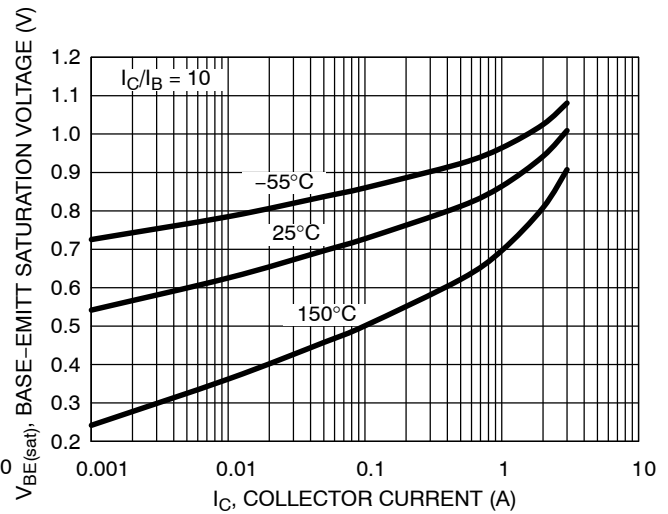


Figure 9. Base-Emitt Saturation Voltage

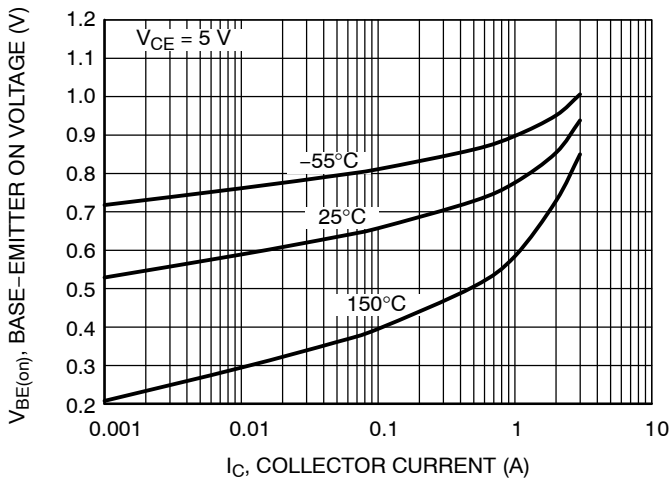


Figure 10. Base-Emitt "On" Voltage

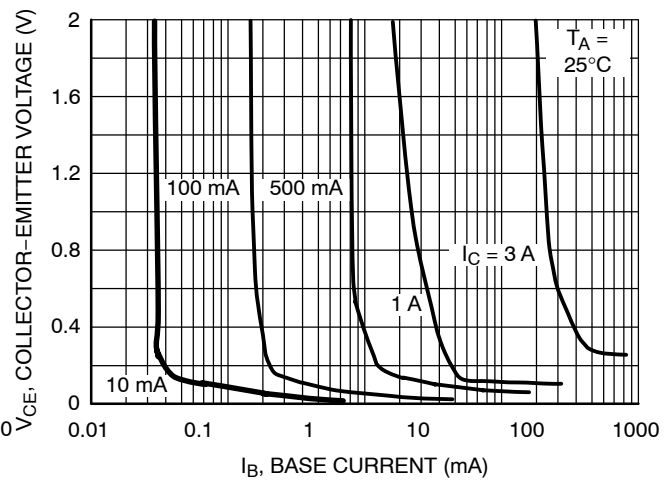


Figure 11. Collector Saturation Region

MJD31, MJD31C (NPN), MJD32, MJD32C (PNP)

TYPICAL CHARACTERISTICS – MJD31, MJD31C (NPN)

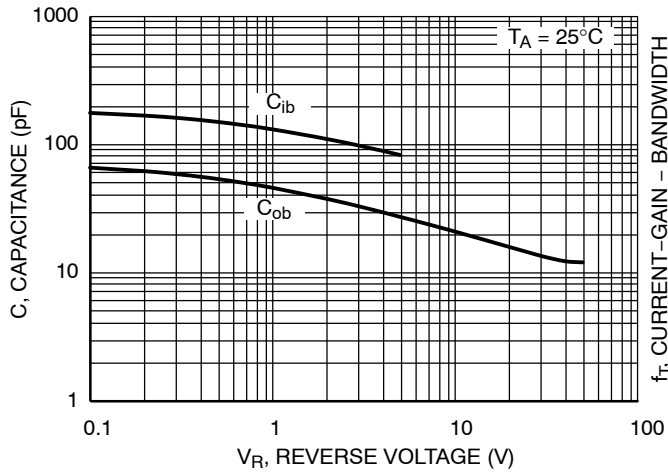


Figure 12. Capacitance

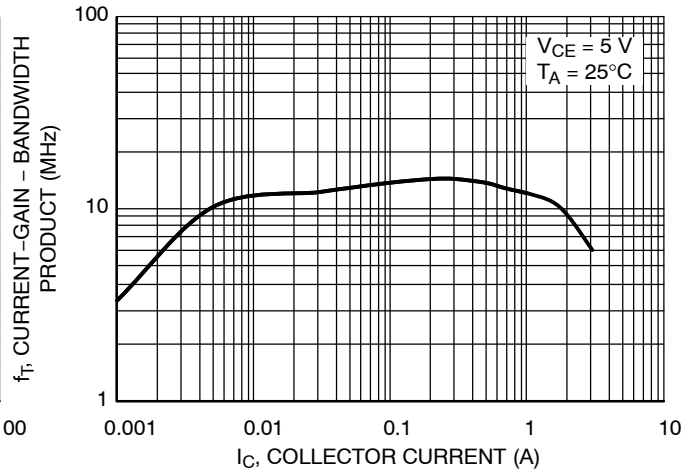


Figure 13. Current-Gain-Bandwidth Product

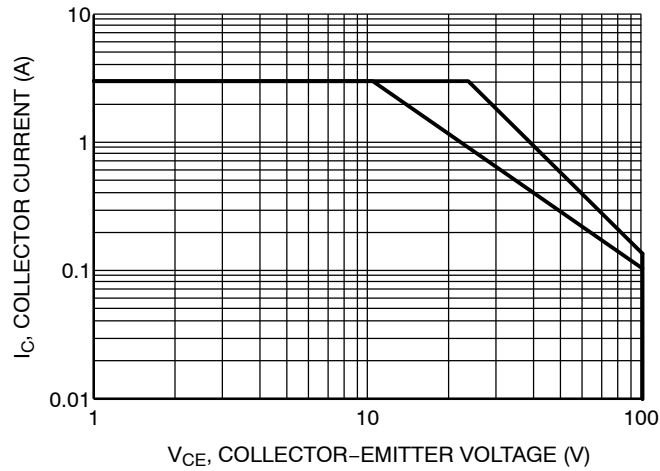


Figure 14. Safe Operating Area

MJD31, MJD31C (NPN), MJD32, MJD32C (PNP)

TYPICAL CHARACTERISTICS – MJD32, MJD32C (PNP)

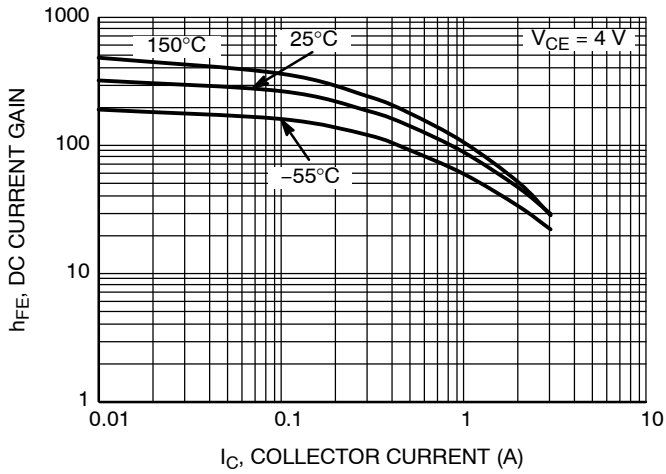


Figure 15. DC Current Gain at $V_{CE} = 4\text{ V}$

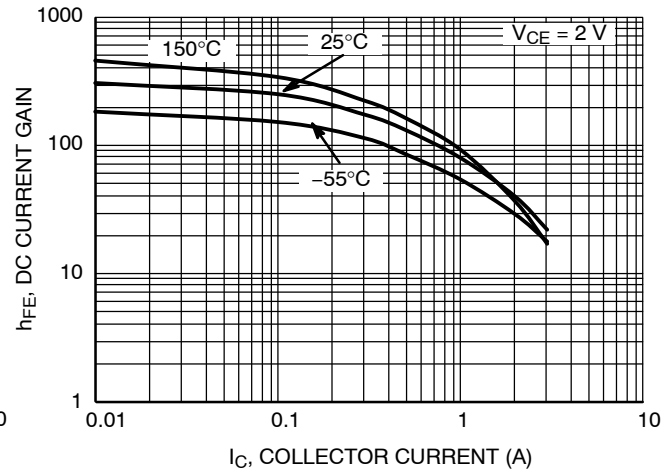


Figure 16. DC Current Gain at $V_{CE} = 2\text{ V}$

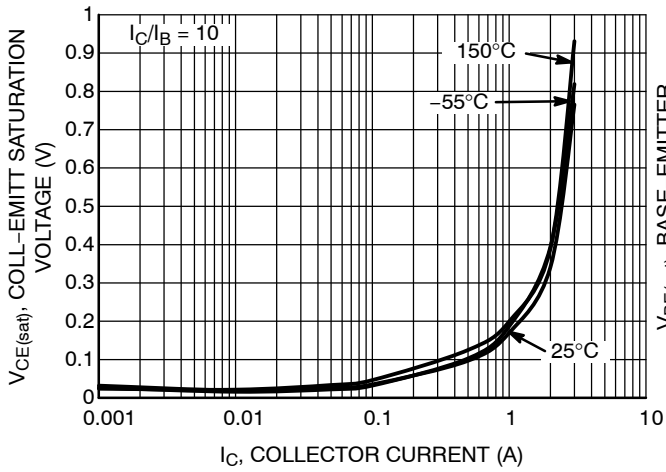


Figure 17. Collector-Emitter Saturation Voltage

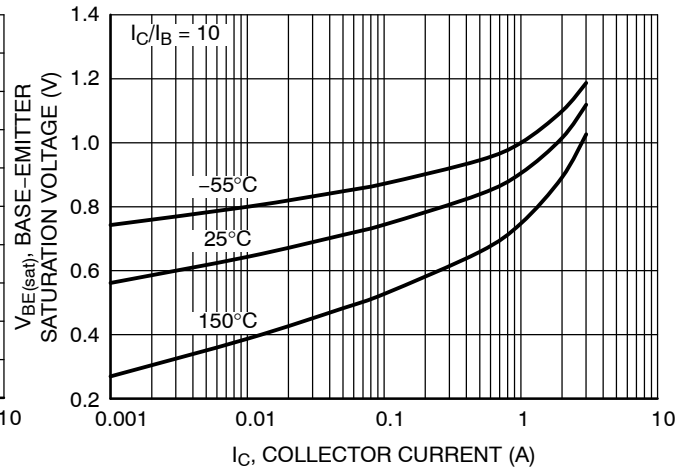


Figure 18. Base-Emitter Saturation Voltage

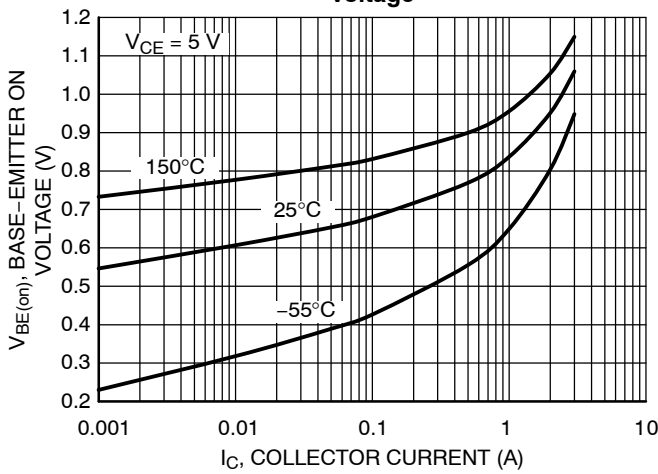


Figure 19. Base-Emitter "On" Voltage

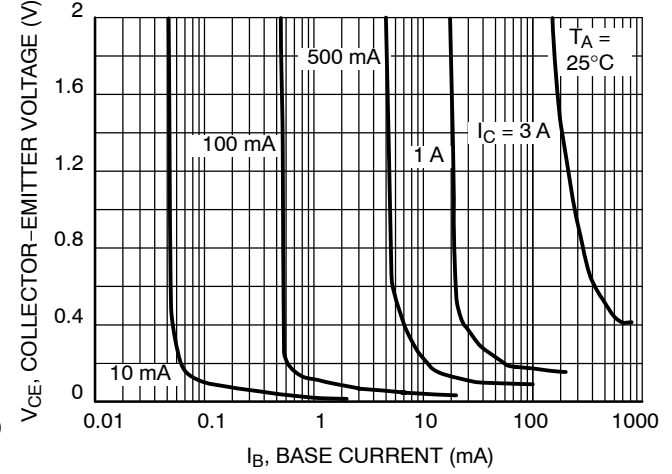


Figure 20. Collector Saturation Region

MJD31, MJD31C (NPN), MJD32, MJD32C (PNP)

TYPICAL CHARACTERISTICS

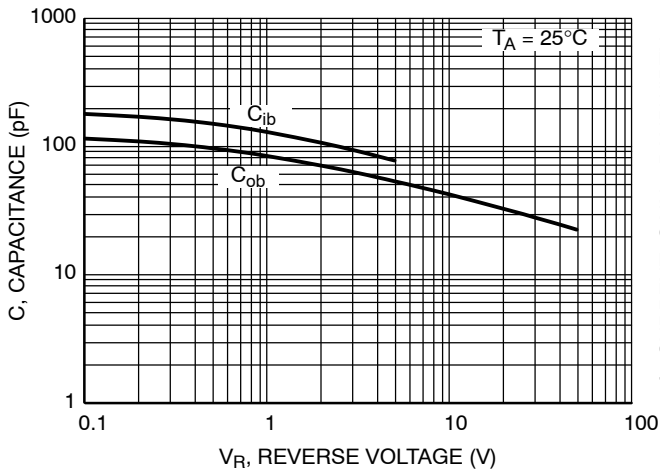


Figure 21. Capacitance

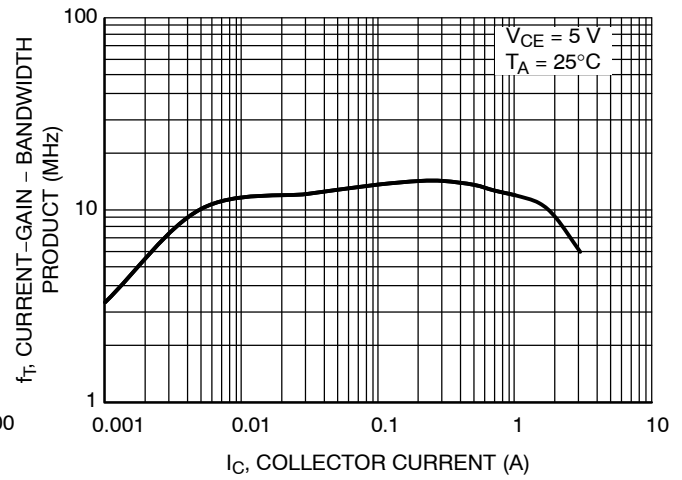


Figure 22. Current-Gain-Bandwidth Product

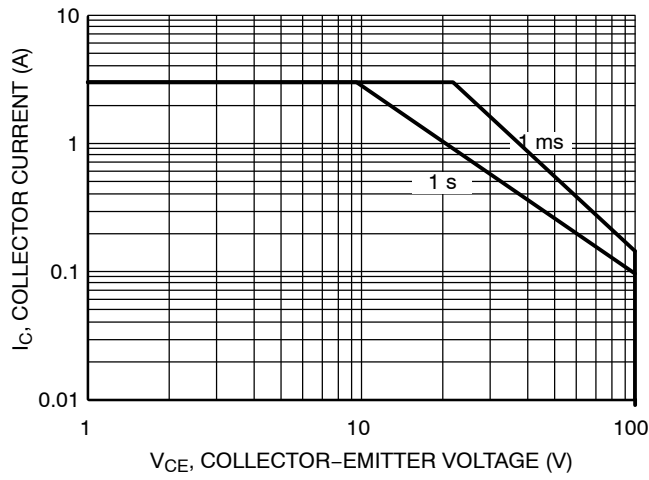


Figure 23. Safe Operating Area

MJD31, MJD31C (NPN), MJD32, MJD32C (PNP)

ORDERING INFORMATION

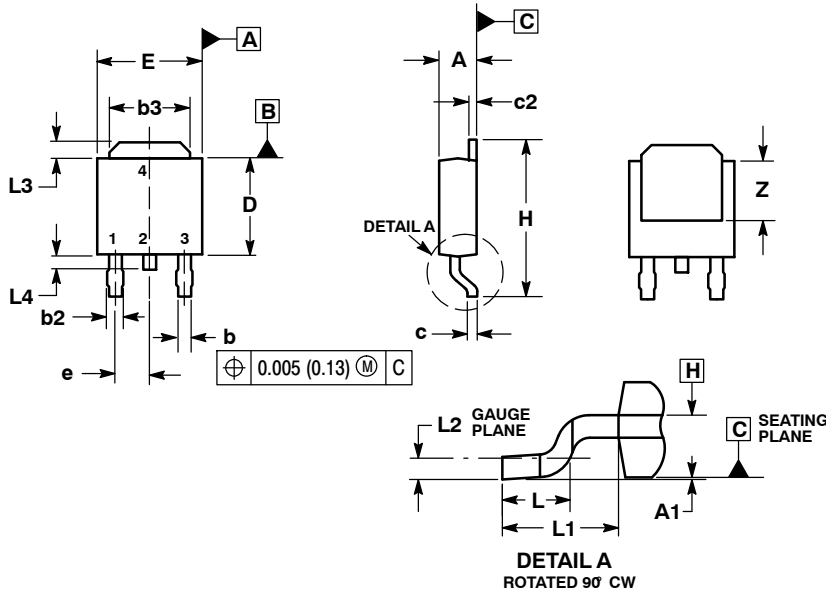
Device	Package Type	Package	Shipping†
MJD31CG	DPAK (Pb-Free)	369C	75 Units / Rail
MJD31C1G	DPAK-3 (Pb-Free)	369D	75 Units / Rail
MJD31CRLG	DPAK (Pb-Free)	369C	1800 Tape & Reel
MJD31CT4G	DPAK (Pb-Free)	369C	2500 Tape & Reel
MJD31T4G	DPAK (Pb-Free)	369C	2500 Tape & Reel
MJD32CG	DPAK (Pb-Free)	369C	75 Units / Rail
MJD32CRLG	DPAK (Pb-Free)	369C	1800 Tape & Reel
MJD32CT4	DPAK	369C	2500 Tape & Reel
MJD32CT4G	DPAK (Pb-Free)	369C	2500 Tape & Reel
MJD32RLG	DPAK (Pb-Free)	369C	1800 Tape & Reel
MJD32T4G	DPAK (Pb-Free)	369C	2500 Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

MJD31, MJD31C (NPN), MJD32, MJD32C (PNP)

PACKAGE DIMENSIONS

DPAK CASE 369C-01 ISSUE D

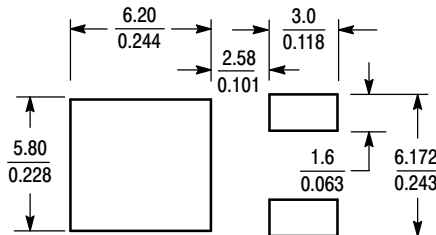


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: INCHES.
3. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS b3, L3 and Z.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.006 INCHES PER SIDE.
5. DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
6. DATUMS A AND B ARE DETERMINED AT DATUM PLANE H.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.086	0.094	2.18	2.38
A1	0.000	0.005	0.00	0.13
b	0.025	0.035	0.63	0.89
b2	0.030	0.045	0.76	1.14
b3	0.180	0.215	4.57	5.46
c	0.018	0.024	0.46	0.61
c2	0.018	0.024	0.46	0.61
D	0.235	0.245	5.97	6.22
E	0.250	0.265	6.35	6.73
e	0.090 BSC		2.29 BSC	
H	0.370	0.410	9.40	10.41
L	0.055	0.070	1.40	1.78
L1	0.108 REF		2.74 REF	
L2	0.020 BSC		0.51 BSC	
L3	0.035	0.050	0.89	1.27
L4	---	0.040	---	1.01
Z	0.155	---	3.93	---

SOLDERING FOOTPRINT*



SCALE 3:1 ($\frac{\text{mm}}{\text{inches}}$)

STYLE 1:

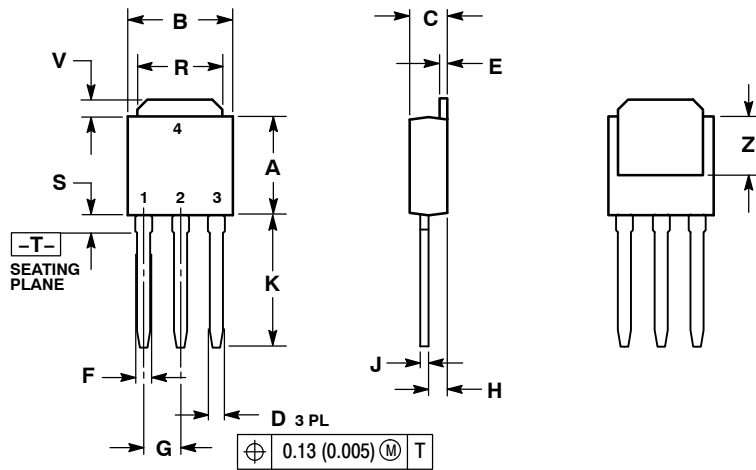
- PIN 1. BASE
- COLLECTOR
- EMITTER
- COLLECTOR

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

MJD31, MJD31C (NPN), MJD32, MJD32C (PNP)

PACKAGE DIMENSIONS

IPAK
CASE 369D-01
ISSUE C



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.235	0.245	5.97	6.35
B	0.250	0.265	6.35	6.73
C	0.086	0.094	2.19	2.38
D	0.027	0.035	0.69	0.88
E	0.018	0.023	0.46	0.58
F	0.037	0.045	0.94	1.14
G	0.090 BSC		2.29 BSC	
H	0.034	0.040	0.87	1.01
J	0.018	0.023	0.46	0.58
K	0.350	0.380	8.89	9.65
R	0.180	0.215	4.45	5.45
S	0.025	0.040	0.63	1.01
V	0.035	0.050	0.89	1.27
Z	0.155	---	3.93	---

STYLE 1:

- PIN 1: BASE
2. COLLECTOR
3. EMITTER
4. COLLECTOR

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